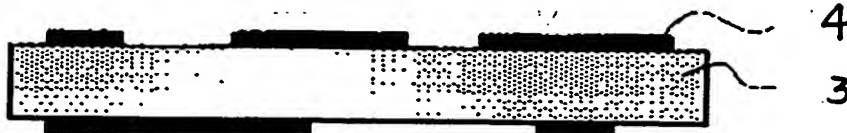
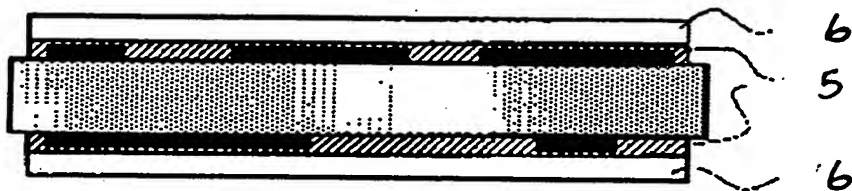


### FIG. 3

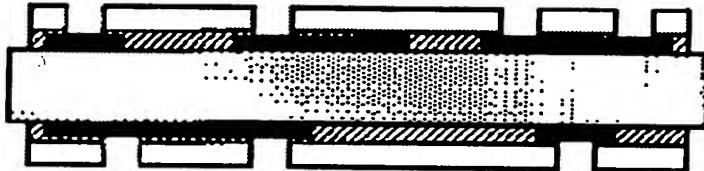
(a) core substrate



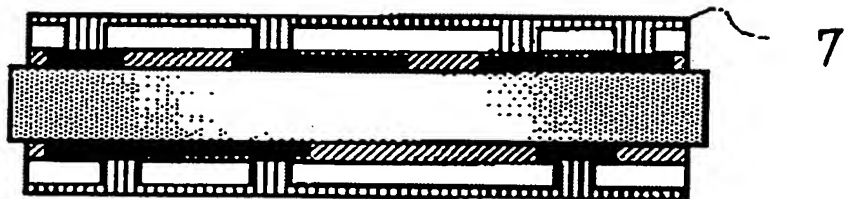
(b) first interlayer insulation layer formation



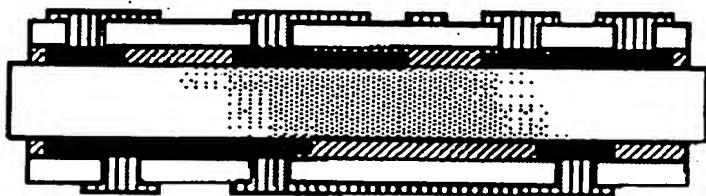
(c) via-hole perforation



(d) via fill plating

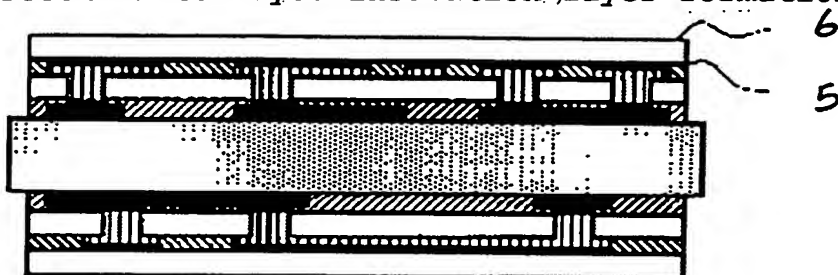


(e) first buildup layer pattern formation

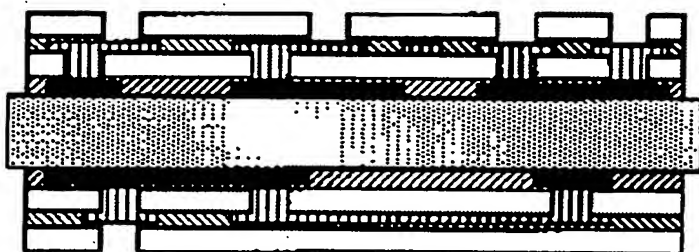


**FIG. 4**

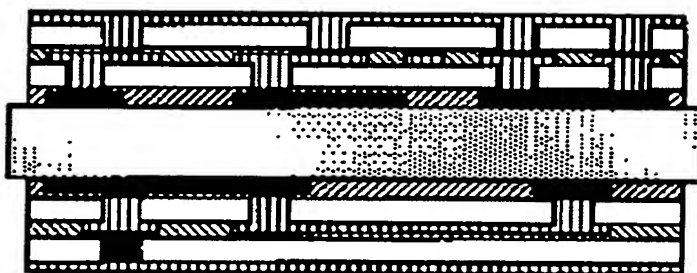
(e) second interlayer insulation layer formation



(b) via-hole perforation



(c) via fill plating



(d) second buildup layer pattern formation

